

W22

2U Passive Air Cooler

PRODUCT SPECIFICATIONS

Specification Version: 12/31/2024

(Specifications are subject to change without notice)

W22 | LGA 5964**Model Number: W22**

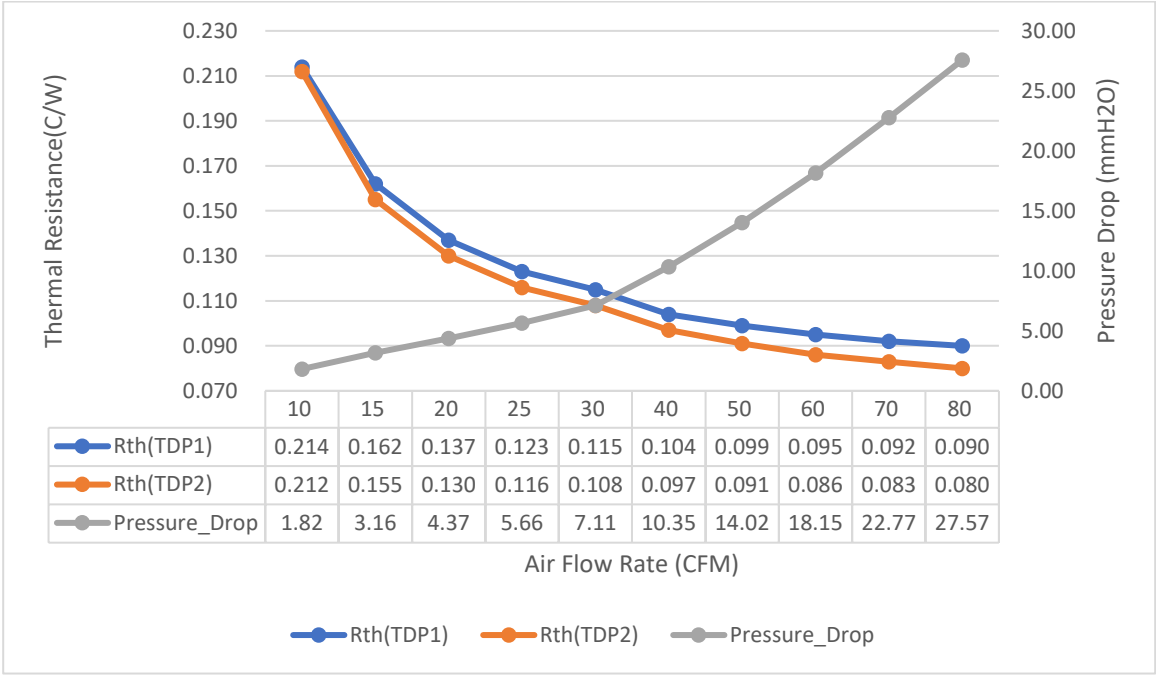
- Recommend for LGA 5964 Processor
- Passive Air Cooler for 2U Server and Up

Overall Specification

Dimension	130.0 x 93.0 x 70.0 mm
Weight	738g±10g
Material	Vapor Chamber + Heatpipe + Aluminum Fins
Thermal Interface Material	Shin-Etsu X23-8079-2 (or equivalent) Pre-Printed Tflex HD7.5 (or equivalent) Pre-Applied
TDP	Fully Support 400W at 41°C Ambient Temperature and 40 CFM Fully Support 400W at 36°C Ambient Temperature and 30 CFM

Performance Chart: W22 Thermal Resistance

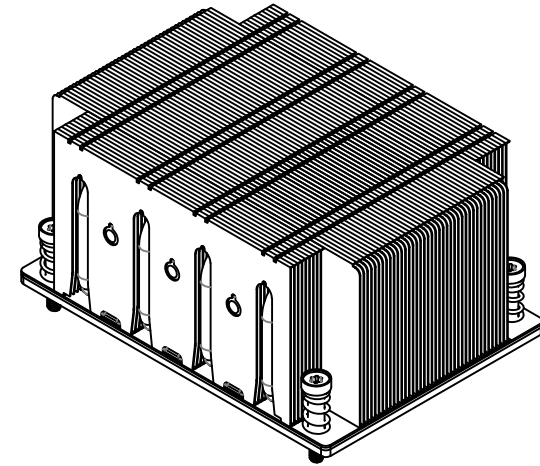
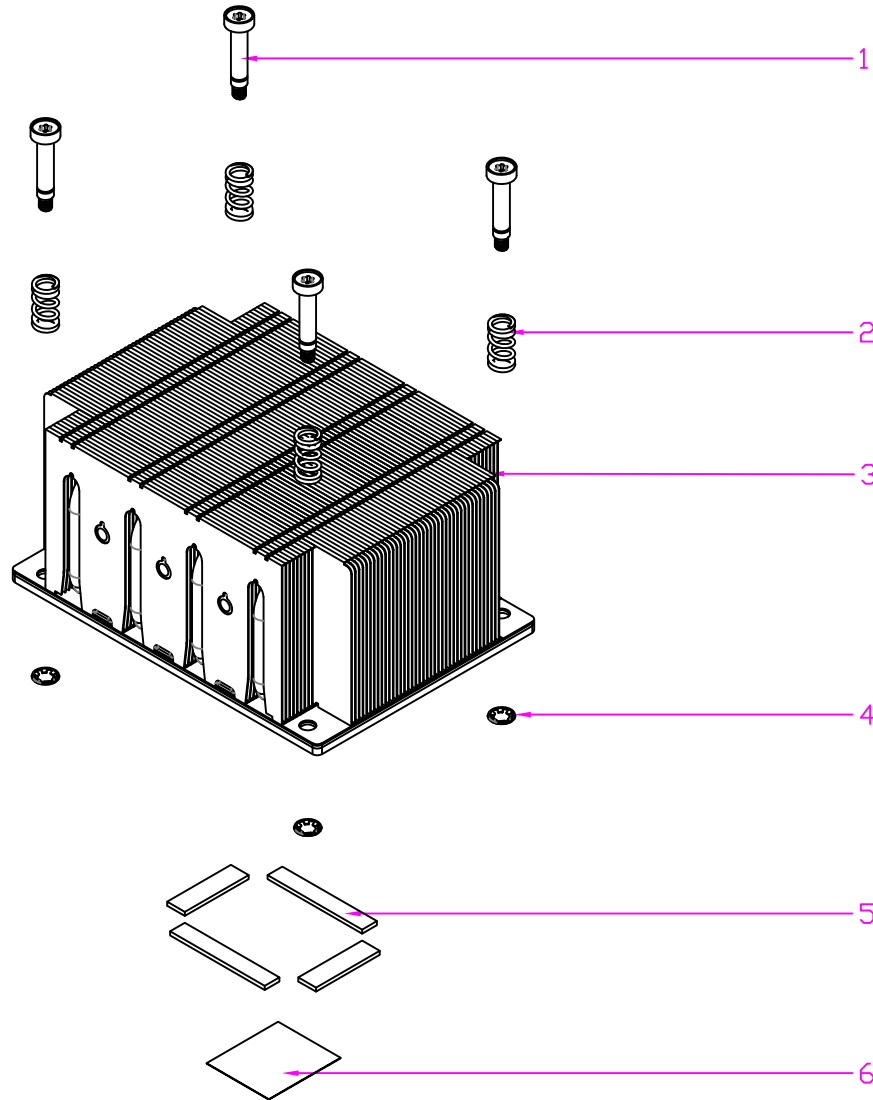
Thermal Resistance vs. Air Flow Rate



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REV#	DESCRIPTION	CHECKER	DATE
0.0	INITIAL RELEASE	MichaelF	11/11/24

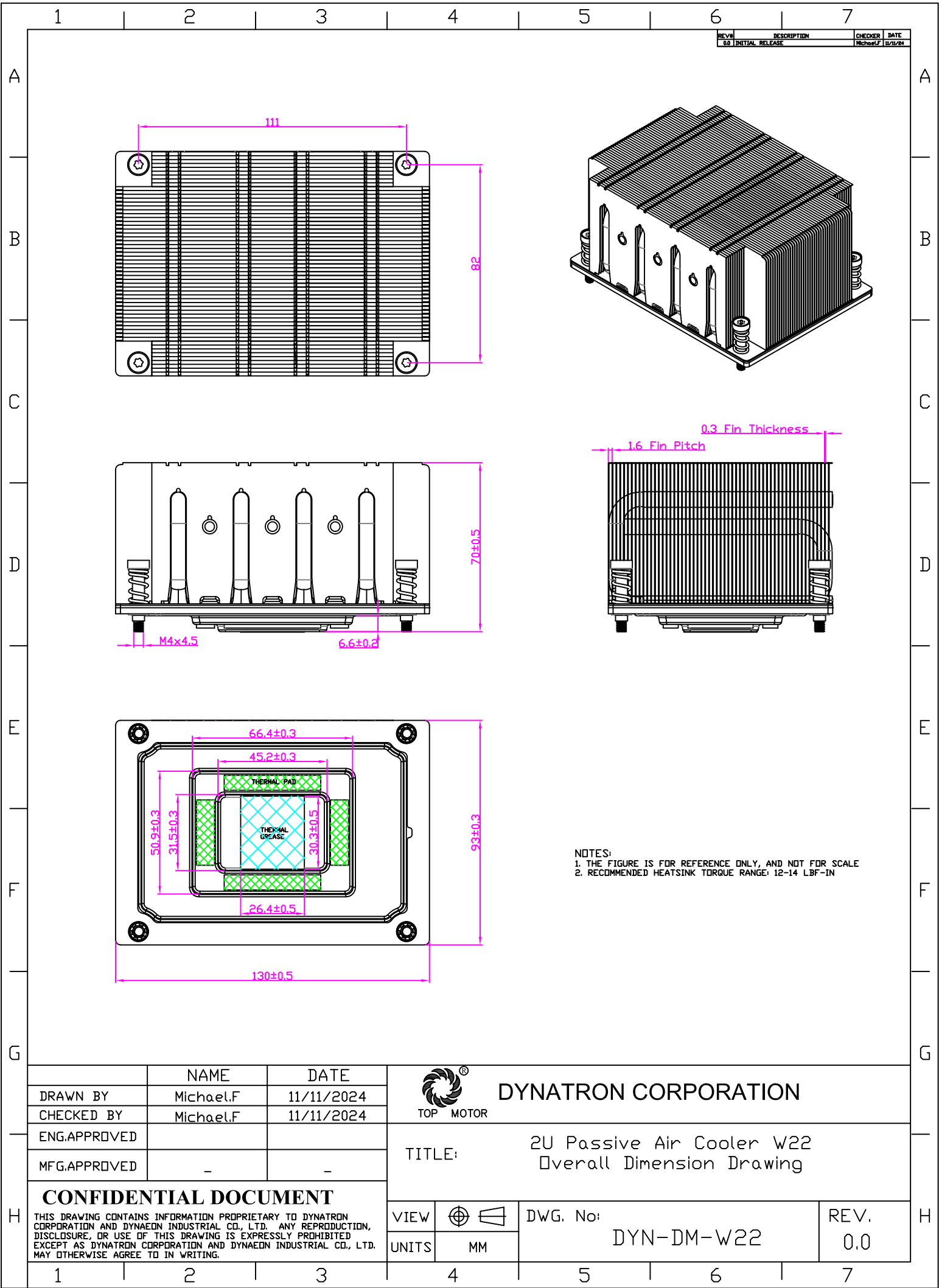


6	THERMAL GREASE	SHIN-ETSU X-23-8079-2 OR EQUIVALENT	N/A
5	THERMAL PAD SET	TFLEX HD7.5 OR EQUIVALENT	1
4	HEATSINK SCREW CLIP	STEEL	4
3	HEATSINK	HEAT PIPES, SK7 REINFORCEMENT BRACKET, COPPER VC, AL1100 FIN	1
2	HEATSINK SPRING	SWC	4
1	HEATSINK SCREW	STEEL	4
ITEM #	DESCRIPTION	MATERIAL	QTY.

	DATE	NAME	 TOP MOTOR DYNATRON CORPORATION	
DRAWN	11/11/24	Michael F	TITLE: 2U Passive Air Cooler W22 BDM & Exploded Assembly Drawing	
CHECKED	11/11/24	Michael F		
ENG. APPR.				
MFG. APPR.				
QA				
COMMENTS:			DWG. No: DYN-EP-W22	REV 0.0

NOTES:

1. THE FIGURE IS FOR REFERENCE ONLY, AND NOT FOR SCALE



Publication History:

12/31/2024: Thermal resistance vs. Air Flow Rate Release

11/11/2024: Initial Release

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